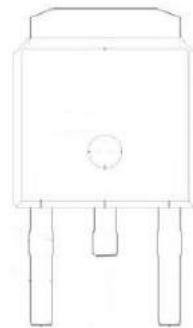
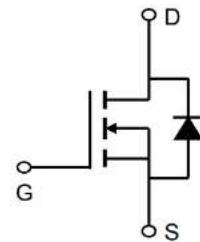


### Description

The 20N02D uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.



### General Features

$V_{DS} = 20V$   $I_D = 20A$

$R_{DS(ON)} < 15m\Omega$  @  $V_{GS}=10V$

### Application

solar road lights

Load switch

Uninterruptible power supply



### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	20	A
$I_D @ T_c=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	13	A
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	6.3	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	5.8	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	50	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	8.1	mJ
$I_{AS}$	Avalanche Current	12.7	A
$P_D @ T_c=25^\circ C$	Total Power Dissipation <sup>4</sup>	20.8	W
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	6	$^\circ C/W$

**20V N-Channel Enhancement Mode MOSFET**
**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	20	22		V
$\Delta BVDSS/\Delta TJ$	BVDSS Temperature Coefficient	Reference to $25^{\circ}\text{C}$ , $I_D=1\text{mA}$	---	0.018	---	$\text{V}/^{\circ}\text{C}$
VGS(th)	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.50	0.65	1.0	V
RDS(ON)	Static Drain-Source On-Resistance	$V_{GS}=4.5\text{V}, I_D=7.6\text{A}$		12	15	$\text{m}\Omega$
RDS(ON)	Static Drain-Source On-Resistance	$V_{GS}=2.5\text{V}, I_D=3.5\text{A}$		15.5	20	
RDS(ON)	Static Drain-Source On-Resistance	$V_{GS}=1.8\text{V}, I_D=2.5\text{A}$		20.5	35	
IDSS	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}, V_{GS}=0\text{V}$			1	$\mu\text{A}$
IGSS	Gate-Body Leakage Current	$V_{GS}=\pm 10\text{V}, V_{DS}=0\text{V}$			$\pm 100$	nA
$C_{iss}$	Input Capacitance	$V_{DS}=10\text{V}, V_{GS}=0\text{V}, f=1\text{MHZ}$		888		pF
$C_{oss}$	Output Capacitance			133		
$C_{rss}$	Reverse Transfer Capacitance			117		
$Q_g$	Total Gate Charge	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, I_D=6.8\text{A}$		11.05		nC
$Q_{gs}$	Gate-Source Charge			1.73		
$Q_{gd}$	Gate-Drain Charge			3.1		
$t_{D(on)}$	Turn-on Delay Time	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, I_D=6.8\text{A}$ $R_{GEN}=3\Omega$		7		ns
$t_r$	Turn-on Rise Time			46		
$t_{D(off)}$	Turn-off Delay Time			30		
$t_f$	Turn-off fall Time			52		
$V_{SD}$	Diode Forward Voltage	$I_S=7.6\text{A}, V_{GS}=0\text{V}$			1.2	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature
- 4、The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

**Typical Characteristics**

### Typical Characteristics

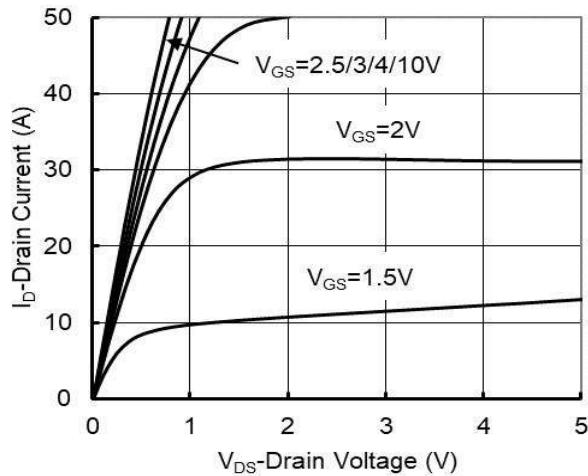


Figure 1. Output Characteristics

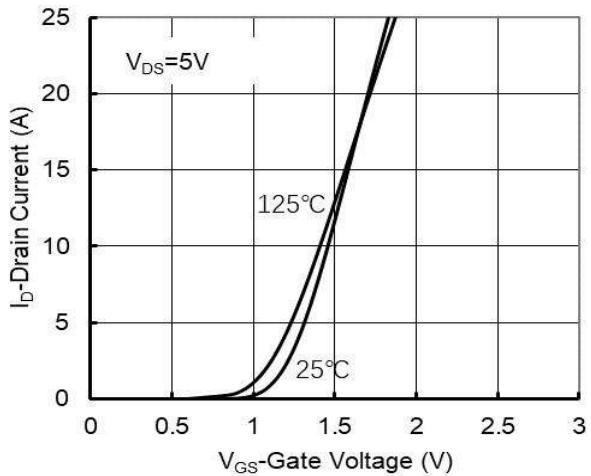


Figure 2. Transfer Characteristics

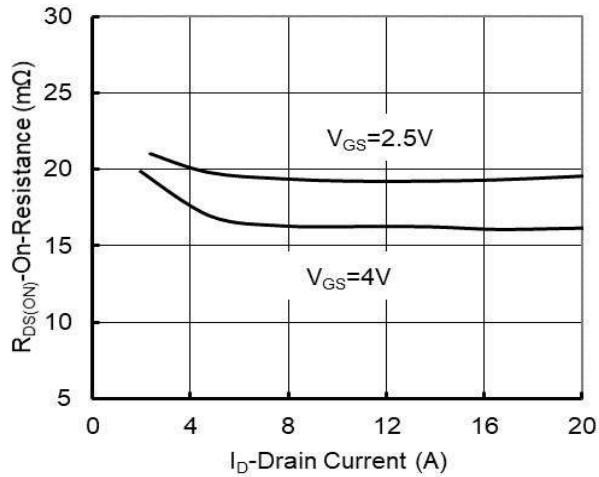


Figure 3: On-Resistance vs. Drain Current

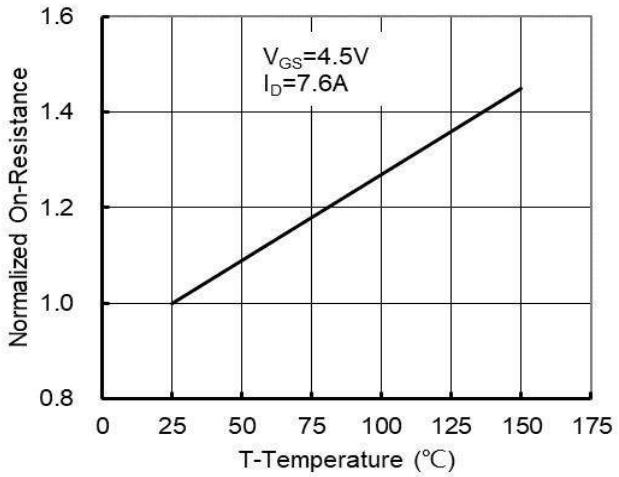


Figure 4: On-Resistance vs. Junction Temperature and Gate Voltage

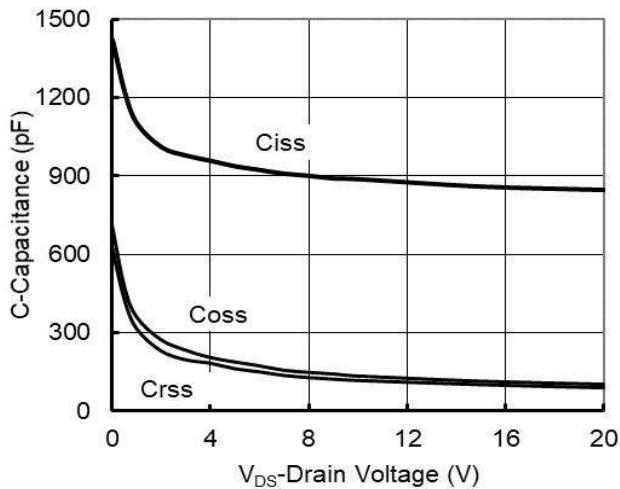


Figure 5. Capacitance Characteristics

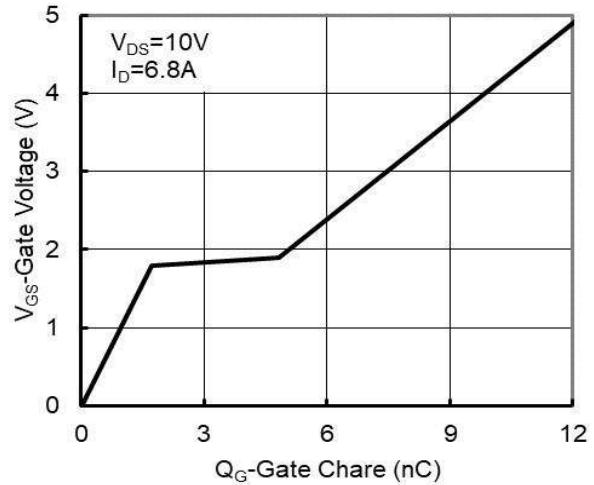
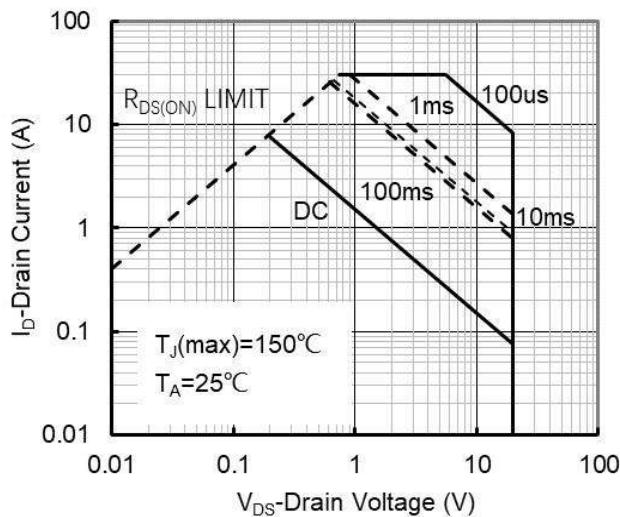
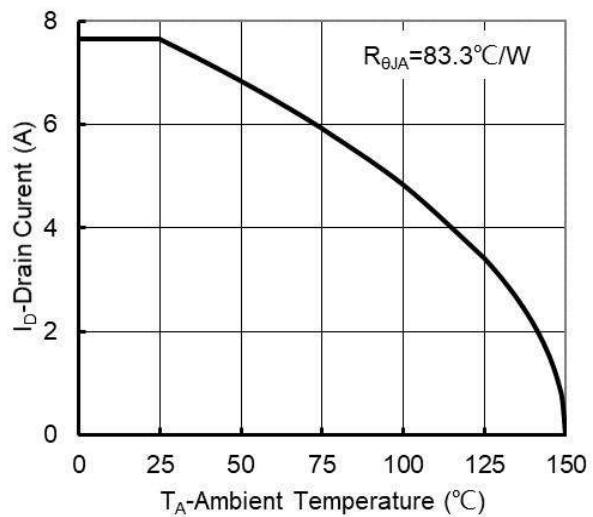
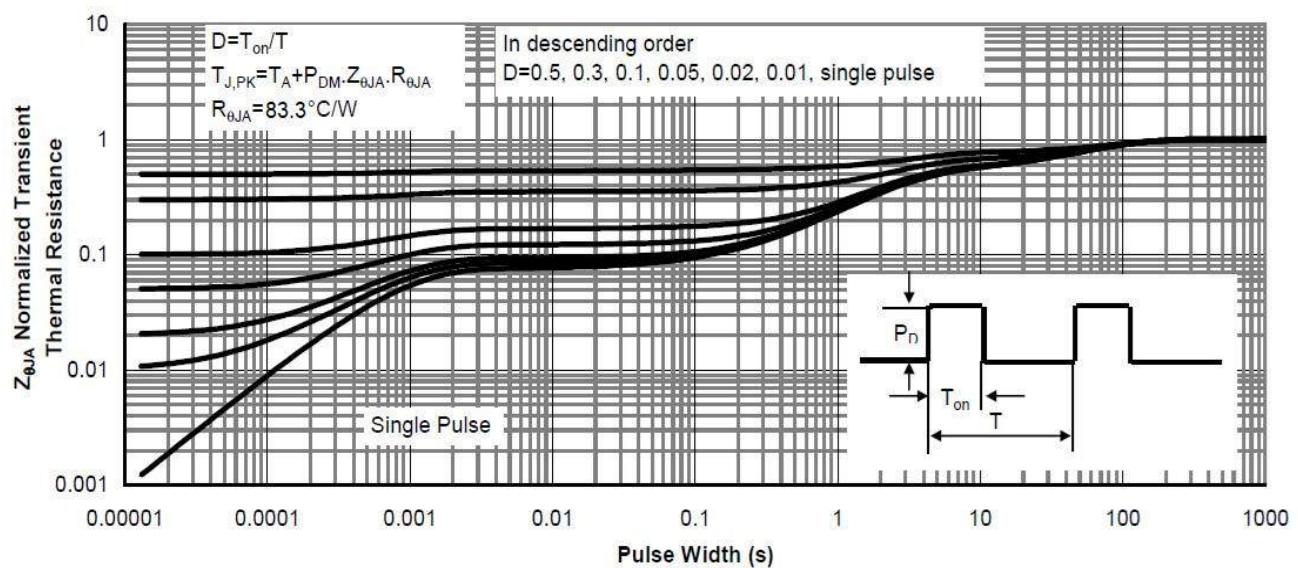
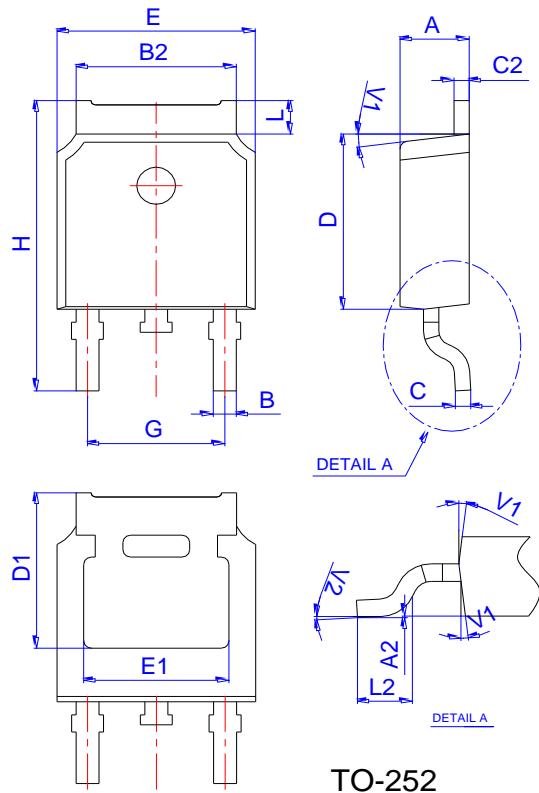
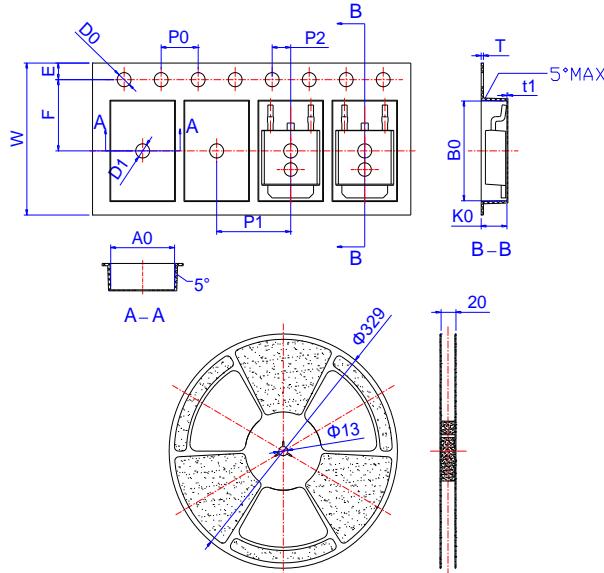


Figure 6. Gate Charge

**20V N-Channel Enhancement Mode MOSFET**

**Figure7. Safe Operation Area**

**Figure8. Maximum Continuous Drain Current vs Ambient Temperature**

**Figure9. Normalized Maximum Transient Thermal Impedance**

**Package Mechanical Data: TO-252-3L**

**TO-252**

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

**Reel Specification-TO-252**


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583